DATA SHEET

SKY65385-11: 791 to 821 MHz Variable Gain Amplifier

Applications

- WCDMA base stations
- Femto cells

Features

- Frequency range: 791 to 821 MHz
- High gain: > 34 dB
- Attenuation range: > 30 dB
- OP1dB: > +30 dBm
- ACLR < -65 dBc for P_{OUT} = +12 dBm
- Single DC supply: +5 V
- Small MCM (12-pin, 8.385 x 8.385 mm) SMT package (MSL3, 260 °C per JEDEC J-STD-020)

Skyworks Green™ products are compliant with all applicable legislation and are halogen-free. For additional information, refer to *Skyworks Definition of Green™*, document number SQ04–0074.

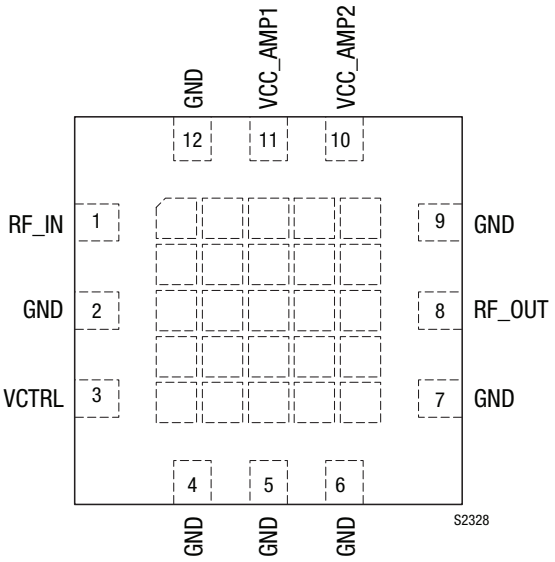

Figure 2. SKY65385-11 Pinout (Top View)

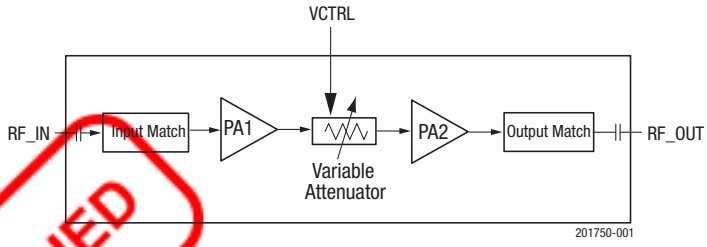

Figure 1. SKY65385-11 Block Diagram

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Description

The Skyworks SKY65385-11 is a high-linearity, variable gain amplifier (VGA) module. The device includes an input amplifier driver, a variable voltage attenuator (VVA), and an output power amplifier (PA). The two amplifiers and voltage attenuator are optimized for superior ACLR performance with WCDMA signals.

The high linearity (high OP1dB, OIP3, and ACLR) and high efficiency of this device make it ideal for use at the final stage (or close to the final stage) of a WCDMA transmit chain.

The output of the first PA (PA1) is matched to the input of the VVA. The output of the VVA is matched to the input of the second PA (PA2). The RF_IN and RF_OUT signals (pins 1 and 8, respectively) are both internally matched, including DC blocking capacitors.

The SKY65385-11 VGA uses low-cost surface mount technology (SMT) in the form of a compact, 8 x 8 mm 12-pin Multi-Chip Module (MCM), which allows for a highly manufacturable low-cost solution. A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

Table 1. SKY65385-11 Signal Descriptions

Pin	Name	Description	Pin	Name	Description
1	RF_IN	RF input	7	GND	Ground
2	GND	Ground	8	RF_OUT	RF output
3	VCTRL	Variable attenuator control voltage	9	GND	Ground
4	GND	Ground	10	VCC_AMP2	Voltage supply for PA2 (after the variable voltage attenuator)
5	GND	Ground	11	VCC_AMP1	Voltage supply for PA1 (before the variable voltage attenuator)
6	GND	Ground	12	GND	Ground

Electrical and Mechanical Specifications

The absolute maximum ratings of the SKY65385-11 are provided in Table 2. The recommended operating conditions are specified in Table 3 and electrical specifications are provided in Table 4.

Typical performance characteristics of the SKY65385-11 are illustrated in Figures 3 to 12.

Table 2. SKY65385-11 Absolute Maximum Ratings[1]

Parameter	Symbol	Minimum	Maximum	Units
Supply voltage	VCC_AMP1, VCC_AMP2		5.5	V
Control voltage	V_{CTL}		5.0	V
RF output power (CW)	P_{OUT}		+29	dBm
Operating case temperature	T_C	–40	+85	°C
Storage case temperature	T_{STG}	–55	+125	°C
Junction temperature	T_J		+150	°C
Thermal resistance (P_{OUT} = +12 dBm)	θ_R		24	C/W
Electrostatic discharge:	ESD			
Charged Device Model (CDM), Class 3			500	V
Human Body Model (HBM), Class 1B			500	V
Machine Model (MM), Class A			50	V

1 Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value.

***ESD HANDLING**: Although this device is designed to be as robust as possible, electrostatic discharge (ESD) can damage this device. This device must be protected at all times from ESD when handling or transporting. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD handling precautions should be used at all times.*

Table 3. SKY65385-11 Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Units
Frequency range	f	791		821	MHz
RF output power (CW)	P_{OUT}			+12	dBm
Supply voltage, measured at terminals of Evaluation Board	VCC_AMP1, VCC_AMP2	4.75	5.00	5.25	V
Variable voltage attenuator control range	VCTRL	0		3.3	V
Ruggedness, load VSWR with no permanent damage	P_{MAX_LOAD}			8:1	
Operating case temperature	T_C	–40		+85	°C

Table 4. SKY65385-11 Electrical Specifications[1]
(VCC_AMP1 = VCC_AMP2 = 5 V, VCTRL = 0 V, f = 805 MHz, T_C = +25 °C, Characteristic Impedance [Z_0] = 50 Ω, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Frequency range	f		791		821	MHz
Small signal gain	|S21|	CW	30.0	34.5		dB
Gain control range	$G_{\_RANGE}$	CW	28	33		dB
Output 1dB compression point	OP1dB	CW	+30	+31		dBm
Third order output intercept point	OIP3	P_{TONE} = +12 dBm, Δf = 1 MHz	+42	+46		dBm
ACLR for P_{OUT} = +12 dBm	ACLR	WCDMA, test mode 1		–70	–65.0	dBc
Noise figure	NF	At maximum gain		4.2	5.0	dB
Input return loss	|S11|	P_{IN} = –20 dBm	10	14		dB
Output return loss	|S22|	P_{IN} = –20 dBm	10	12		dB
Quiescent current	I_Q	No RF		460	510	mA
Operating current	I_{OP}	P_{OUT} = +12 dBm		460	510	mA
Maximum VSWR for stable operation	$VSWR_{\_MAX}$	CW	8:1			–

[1] Performance is guaranteed only under the conditions listed in this table.

Typical Performance Characteristics

(VCC_AMP1 = VCC_AMP2 = 5 V, VCTRL = 0 V, f = 805 MHz, Tc = +25 °C, Characteristic Impedance [Zo] = 50 Ω, Unless Otherwise Noted)

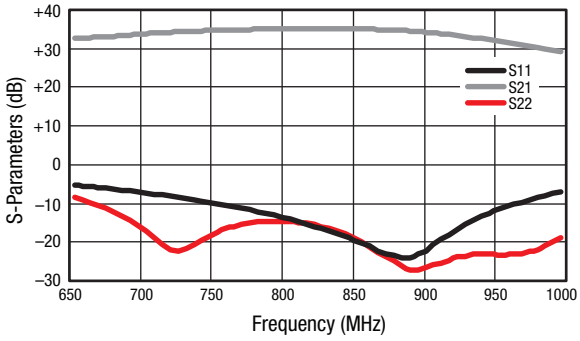


Figure 3. Small Signal Parameters vs Frequency

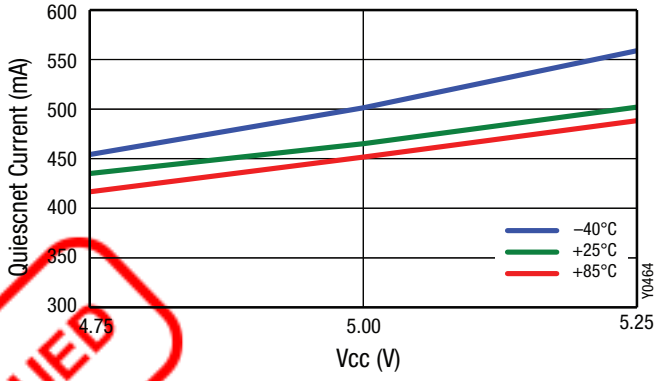


Figure 4. Quiescent Current vs Voltage over Temperature

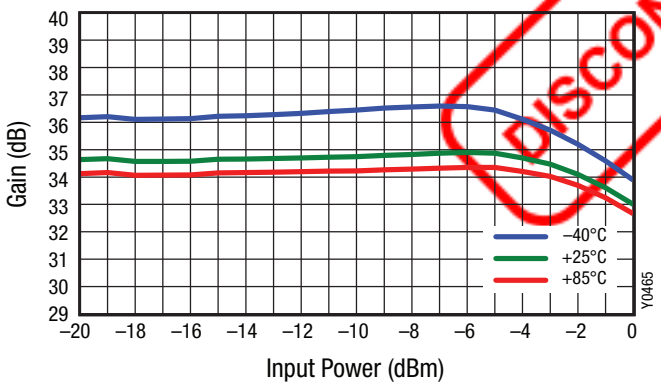


Figure 5. Gain vs Input Power over Temperature

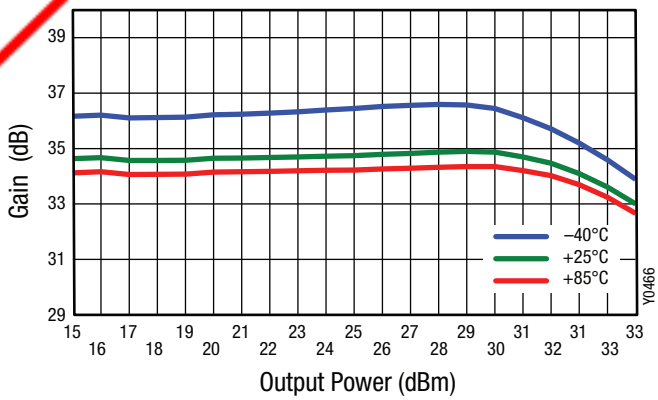


Figure 6. Gain vs Output Power over Temperature

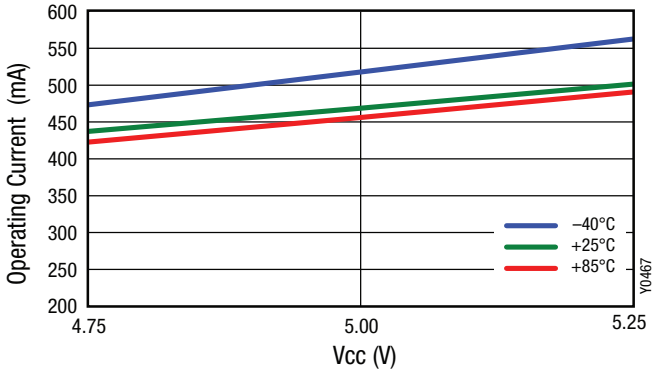


Figure 7. Operating Current vs VCC over Temperature

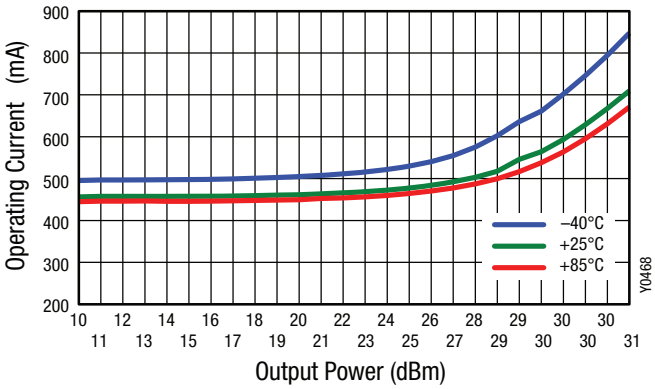


Figure 8. OIP3 vs Output Power

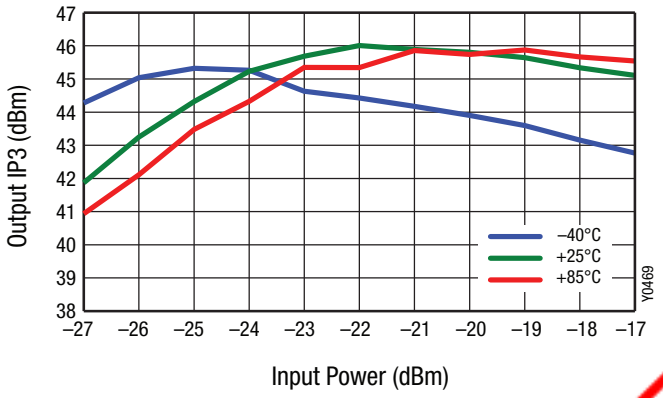


Figure 9. Output IP3 vs Input Power over Temperature

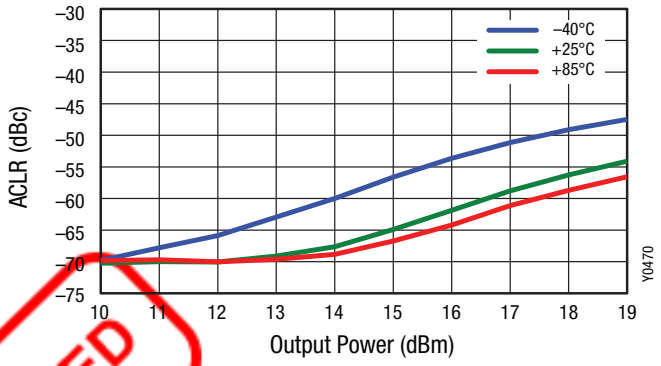


Figure 10. ACLR vs Output Power (WCDMA, TM1)

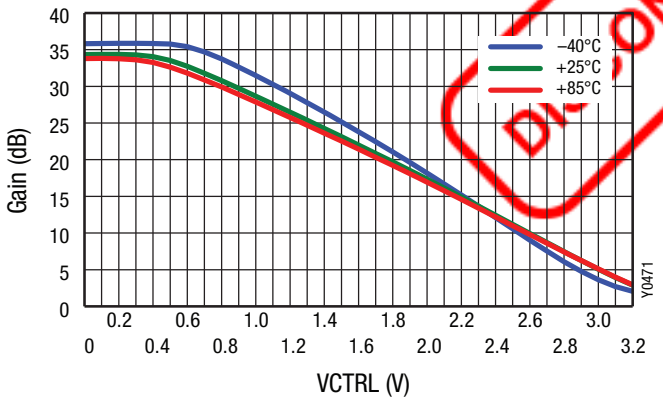


Figure 11. Gain vs VCTRL over Temperature

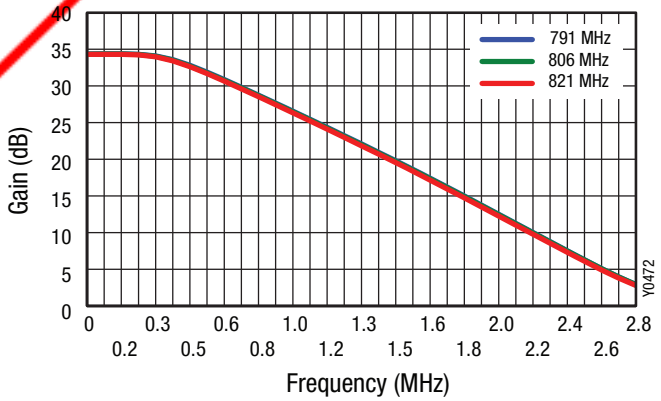


Figure 12. Gain vs VCTRL over Frequency

Evaluation Board Description

The Skyworks SKY65385-11 Evaluation Board is used to test the performance of the SKY65385-11 VGA. An Evaluation Board schematic diagram is provided in Figure 13. An assembly drawing for the Evaluation Board is shown in Figure 14 and the layer detail is provided in Figure 15. The layer detail physical characteristics are noted in Figure 16.

Capacitors C1, C2, and C3 provide DC bias decoupling and RF bypass for VCC_AMP1 (pin 11). Capacitors C4, C5, and C6 provide DC bias decoupling and RF bypass for VCC_AMP2 (pin 10). Capacitor C7 provides decoupling for VCTRL (pin 3).

Pins 1 and 8 are the RF input and output signals, respectively. Pins 2, 4, 5, 6, 7, 9, 12, and the package backside metal are ground pins that provide the DC, RF, and thermal ground.

Testing Procedure

Use the following procedure to set up the SKY65385-11 Evaluation Board for testing:

1. Connect a 5.0 V supply to the VCC_AMP1 and VCC_AMP2 pins. Connect the VCTRL signal to a power supply and set the power supply to 0 V. If available, enable the current limiting function of the power supply to 550 mA.
2. Connect a signal generator to the RF signal input port. Set it to the desired RF frequency at a power level of –20 dBm or less to the Evaluation Board but do NOT enable the RF signal.
3. Connect a spectrum analyzer to the RF signal output port.
4. Enable the power supply.
5. Enable the RF signal.
6. Take measurements.

***CAUTION**: If any of the output signals exceed the rated maximum values, the SKY65385-11 Evaluation Board can be permanently damaged.*

Circuit Design Configurations

The following design considerations are general in nature and must be followed regardless of final use or configuration:

- Proper isolation must be provided between the VCC_AMP1 and VCC_AMP2 pins.
- Paths to ground should be made as short as possible.
- The ground pad of the SKY65385-11 VGA has special electrical and thermal grounding requirements. This pad is the main thermal conduit for heat dissipation. Since the circuit board acts as the heat sink, it must shunt as much heat as possible from the amplifier. As such, design the connection to the ground pad to dissipate the maximum wattage produced to the circuit board. Multiple vias to the grounding layer are required. Filled or capped vias are recommended.
- It is recommended that the layout for the VCC_AMP1 and VCC_AMP2 signals follow what is shown in Figure 14. The VCC_AMP1 and VCC_AMP2 traces can be tied together to share the same power supply. The connecting node should not be placed close to the package pins. The connecting node should be connected closer to components C1 and C4 (see Figure 13) to provide isolation between VCC_AMP1 and VCC_AMP2.

***NOTE:** Junction temperature (Tj) of the device increases with a poor connection to the ground pad and ground. This reduces the life of the device.*

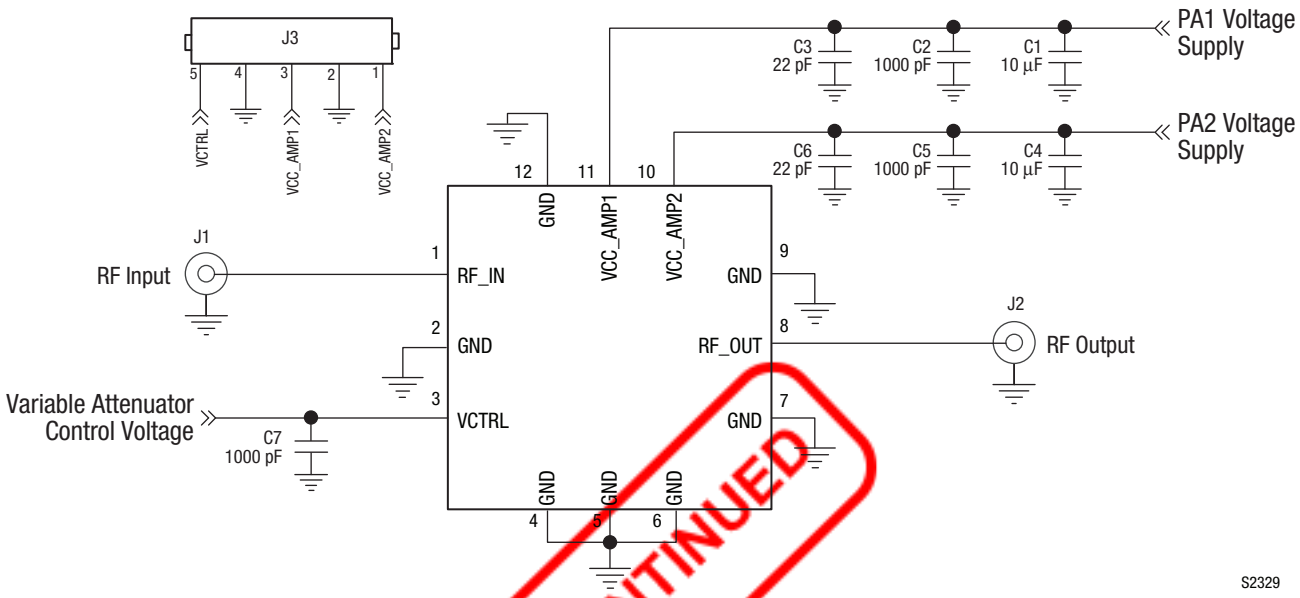


Figure 13. SKY65385-11 Evaluation Board Schematic

Table 5. SKY385-11 Evaluation Board Bill of Materials (BOM)

Reference Designator	Description	Size
C2, C5, C7	Capacitor, ceramic, 1000 pF, COG (NPO), 50 V, +5%, –5%	0603
C1, C4	Capacitor, ceramic, 1000000 pF, X7R, 10 V, +10%, -10%	0805
C3, C6	5404R71-037 Capacitor, ceramic, 22 pF, 50 V, +5%, –5%	0603

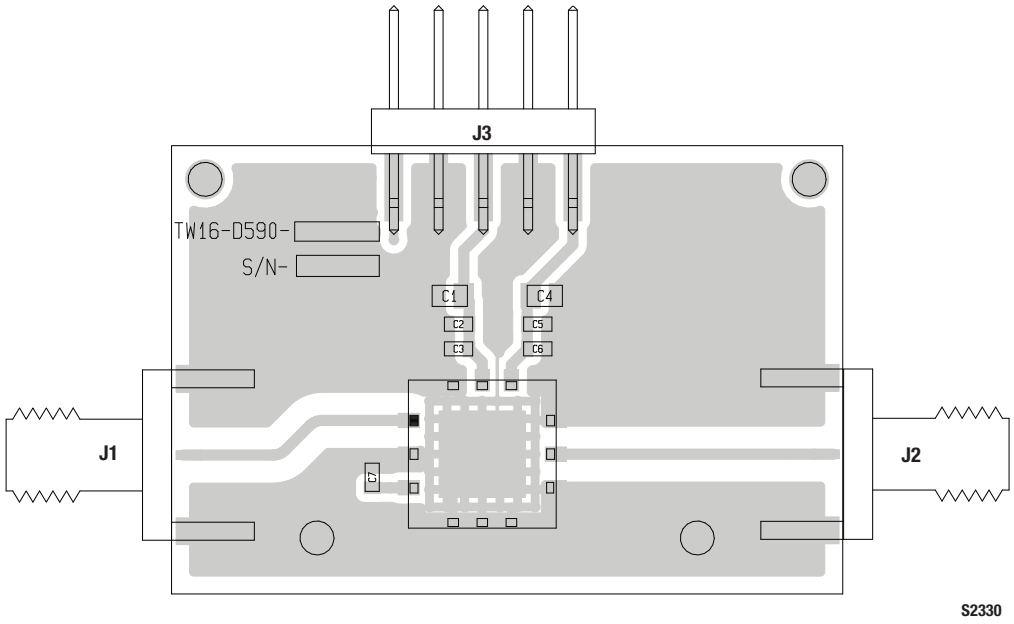


Figure 14. SKY65385-11 Evaluation Board Assembly Drawing

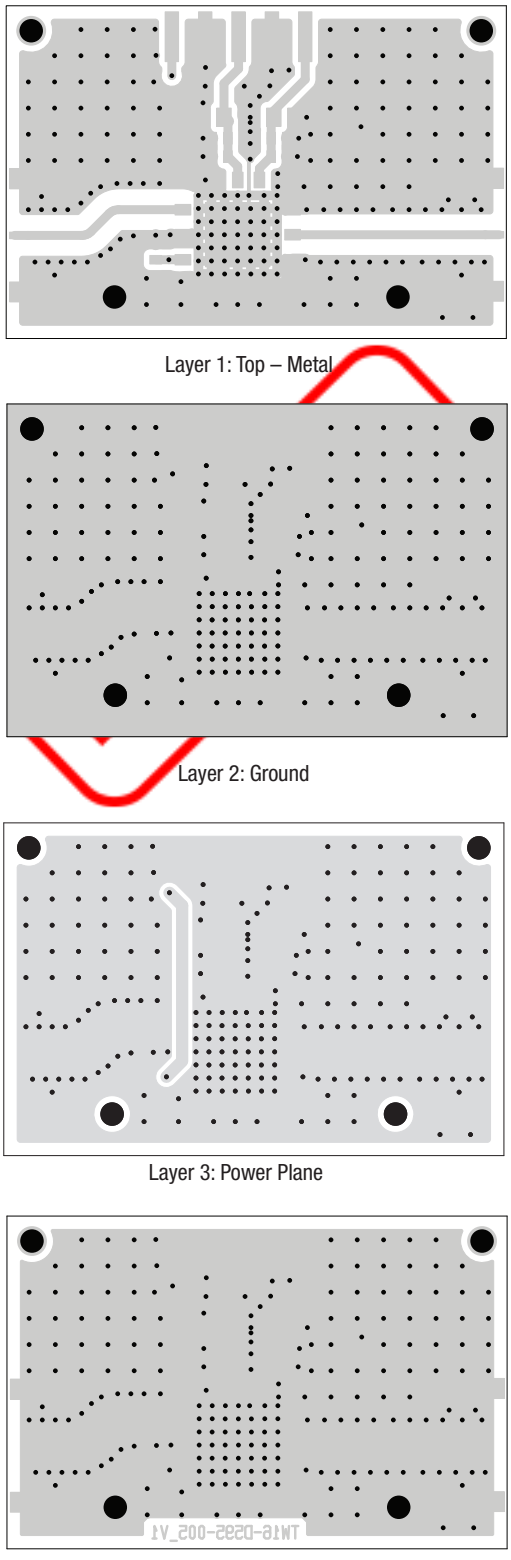


Figure 15. SKY65385-11 Evaluation Board Layer Detail

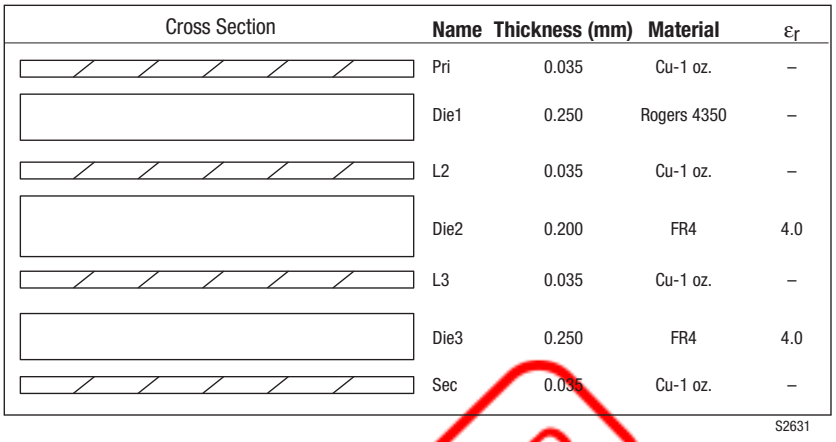


Figure 16. Layer Detail Physical Characteristics

Package Dimensions

The PDB footprint drawing for the SKY65385-11 is shown in Figure 17. A typical part marking is shown in Figure 18. Package dimensions are shown in Figure 19, and tape and reel dimensions are provided in Figure 20.

Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY65385-11 is rated to Moisture Sensitivity Level 3 (MSL3) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, *PCB Design & SMT Assembly/Rework Guidelines for MCM-L Packages*, document number 101752.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.

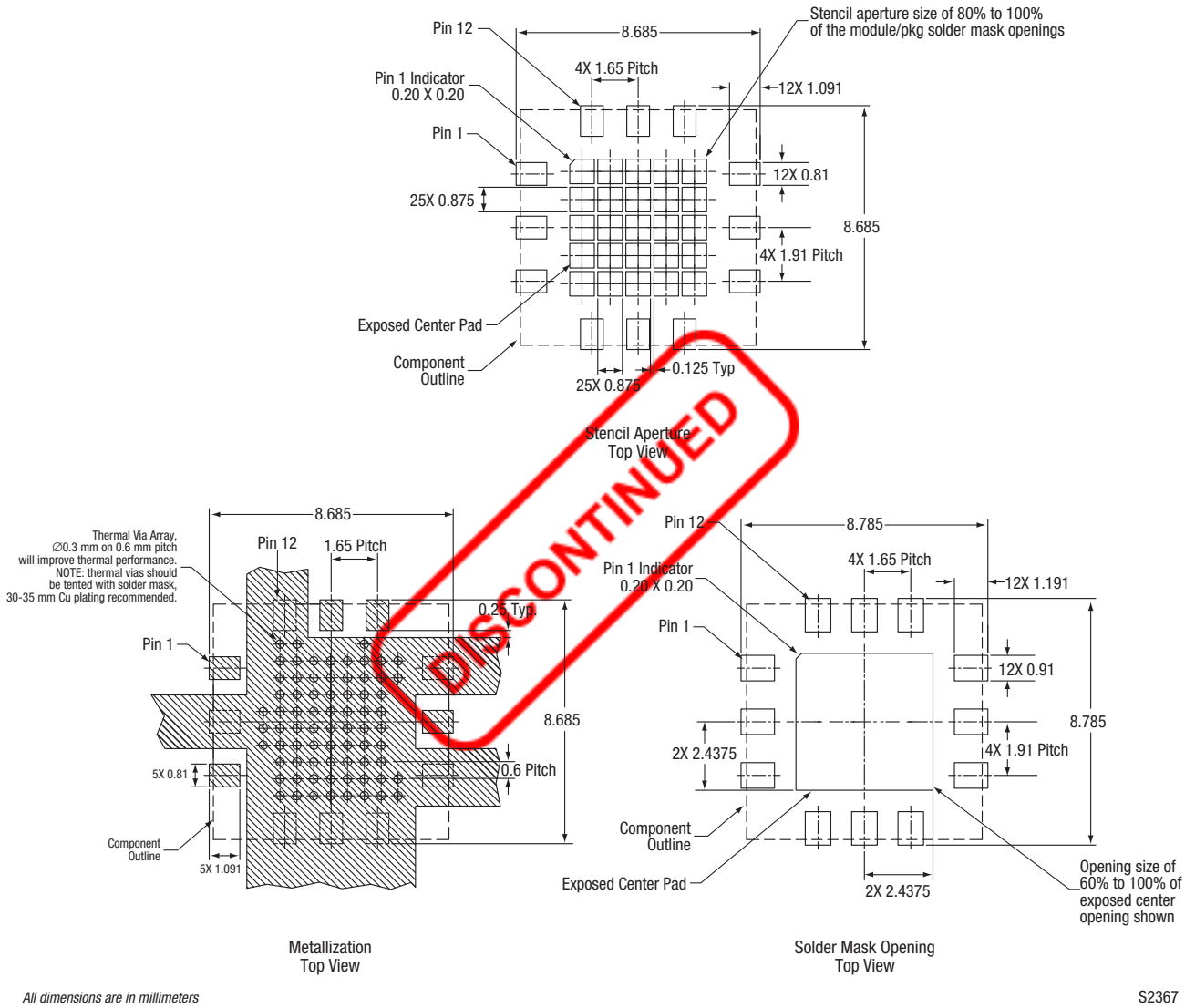


Figure 17. SKY65385-11 PCB Layout Footprint

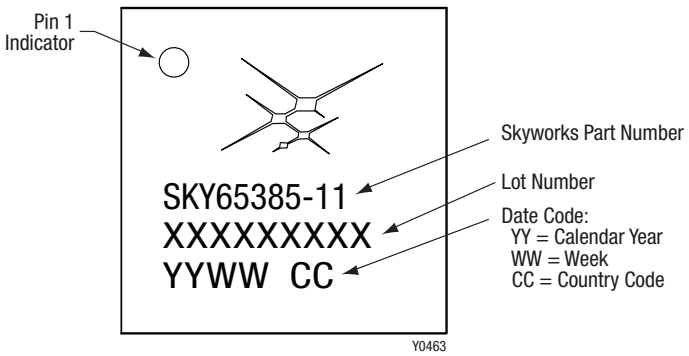
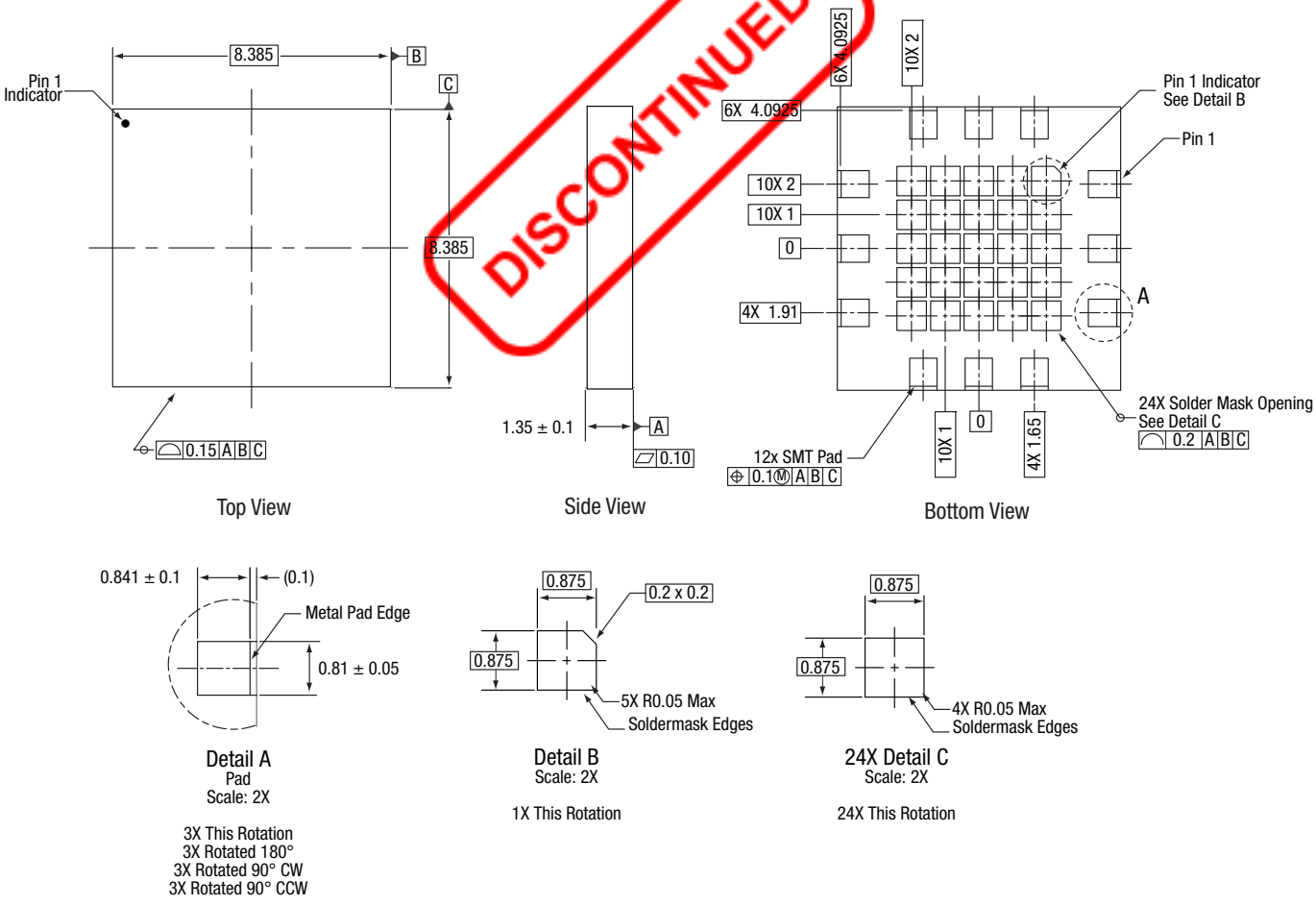


Figure 18. Typical Part Marking

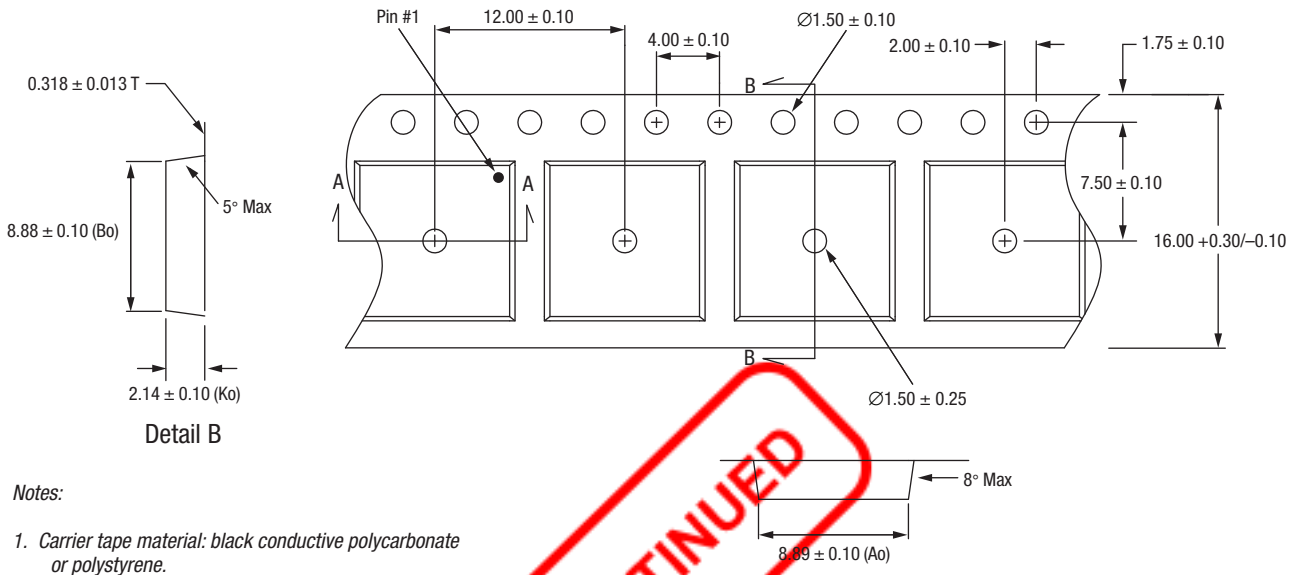


Notes:

1. *Dimensioning and tolerancing according to ASME Y14.5M-1994.*
2. *Pads are metal defined.*
3. *All measurements are in millimeters.*

S2366

Figure 19. SKY65385-11 Package Dimensions



Notes:

1. *Carrier tape material: black conductive polycarbonate or polystyrene.*
2. *Cover tape material: transparent conductive PSA.*
3. *Cover tape size: 13.3 mm width.*
4. *Typical ESD surface resistivity is ≤10^8 Ohms/square per EIA, JEDEC tape and reel specification.*
5. *Tolerance: .XX = ±0.10 mm.*
6. *All measurements are in millimeters.*

Figure 20. SKY65385-11 Tape and Reel Dimensions

Ordering Information

Model Name	Manufacturing Part Number	Evaluation Board Part Number
SKY65385-11 791 to 821 MHz Variable Gain Amplifier	SKY65385-11	SKY65385-11-EVB